

**CHIP STRUCTURE WITH PADS HAVING BUMPS OR WIREBONDED WIRES  
FORMED THEREOVER OR USED TO BE TESTED THERETO**

Appl. No.	:	10/730,834	Confirmation No.
Applicant	:	Nick Kuo, Chiu-Ming Chou, Chien-Kang Chou, Chu-Fu Lin	
Filed	:	December 8, 2003	
TC/A.U.	:	2826	
Examiner	:	ANDUJAR, LEONARDO	
Docket No.	:	MEGP0033USA	
Customer No.	:	27765	

Commissioner for Patents  
P.O. Box 1450  
Alexandria VA 22313-1450

**AMENDMENT AND RESPONSE TO FINAL OFFICE ACTION**

5 Sir:

In response to the Final Office Action mailed January 24, 2007, please amend the above-identified application and consider the remarks as follows:

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

10 **Remarks/Arguments** begin on page 9 of this paper.